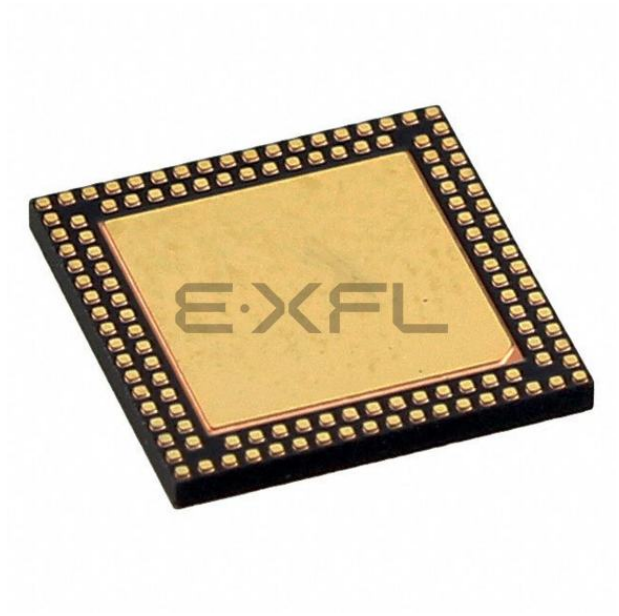

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	124-VFTLA Dual Rows, Exposed Pad
Supplier Device Package	124-VTLA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx350f256lt-i-tl

TABLE 5: PIN NAMES FOR 100-PIN DEVICES

100-PIN TQFP (TOP VIEW)(1,2)

PIC32MX430F064L
PIC32MX450F128L
PIC32MX450F256L
PIC32MX470F512L

100

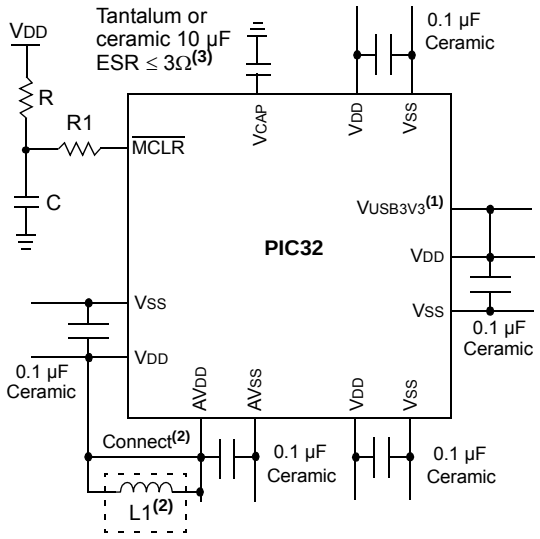
1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	RG15	36	VSS
2	VDD	37	VDD
3	AN22/RPE5/PMD5/RE5	38	TCK/CTED2/RA1
4	AN23/PMD6/RE6	39	RPF13/RF13
5	AN27/PMD7/RE7	40	RPF12/RF12
6	RPC1/RC1	41	AN12/PMA11/RB12
7	RPC2/RC2	42	AN13/PMA10/RB13
8	RPC3/RC3	43	AN14/RPB14/CTED5/PMA1/RB14
9	RPC4/CTED7/RC4	44	AN15/RPB15/OCFB/CTED6/PMA0/RB15
10	AN16/C1IND/RPG6/SCK2/PMA5/RG6	45	VSS
11	AN17/C1INC/RPG7/PMA4/RG7	46	VDD
12	AN18/C2IND/RPG8/PMA3/RG8	47	RPD14/RD14
13	$\overline{\text{MCLR}}$	48	RPD15/RD15
14	AN19/C2INC/RPG9/PMA2/RG9	49	RPF4/PMA9/RF4
15	VSS	50	RPF5/PMA8/RF5
16	VDD	51	USBID/RF3
17	TMS/CTED1/RA0	52	RPF2/RF2
18	RPE8/RE8	53	RPF8/RF8
19	RPE9/RE9	54	VBUS
20	AN5/C1INA/RPB5/VBUSON/RB5	55	VUSB3V3
21	AN4/C1INB/RB4	56	D-
22	PGED3/AN3/C2INA/RPB3/RB3	57	D+
23	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	58	SCL2/RA2
24	PGEC1/AN1/RPB1/CTED12/RB1	59	SDA2/RA3
25	PGED1/AN0/RPB0/RB0	60	TDI/CTED9/RA4
26	PGEC2/AN6/RPB6/RB6	61	TDO/RA5
27	PGED2/AN7/RPB7/CTED3/RB7	62	VDD
28	VREF-/CVREF-/PMA7/RA9	63	OSC1/CLKI/RC12
29	VREF+/CVREF+/PMA6/RA10	64	OSC2/CLKO/RC15
30	AVDD	65	VSS
31	AVSS	66	SCL1/RPA14/RA14
32	AN8/RPB8/CTED10/RB8	67	SDA1/RPA15/RA15
33	AN9/RPB9/CTED4/RB9	68	RPD8/RTCC/RD8
34	CVREFOUT/AN10/RPB10/CTED11/PMA13/RB10	69	RPD9/RD9
35	AN11/PMA12/RB11	70	RPD10/SCK1/PMCS2/RD10

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **Section 31.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

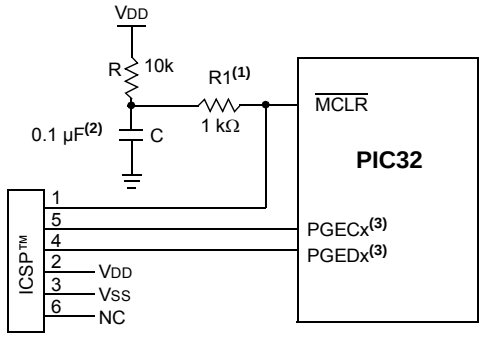
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



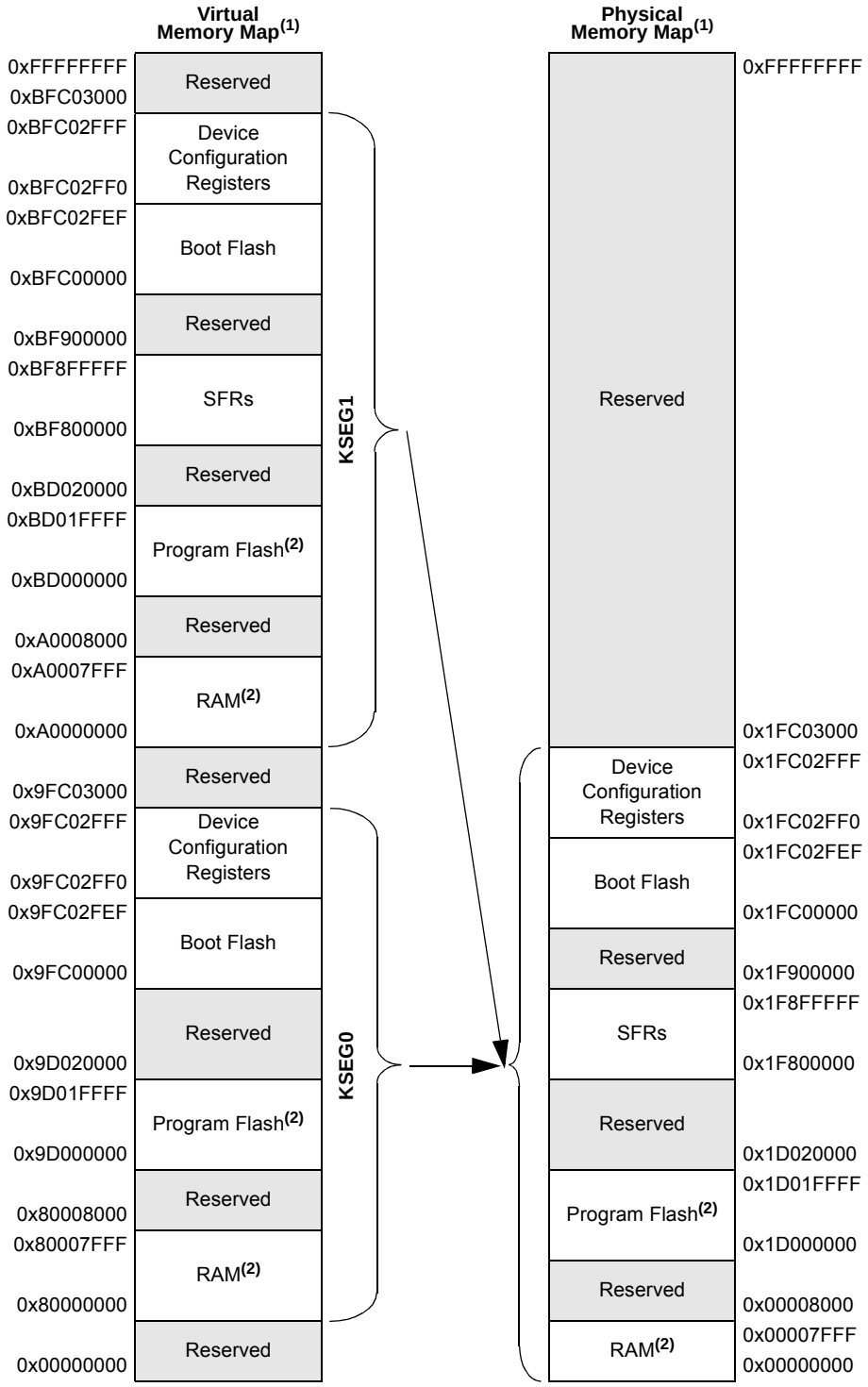
Note 1: 470Ω ≤ R1 ≤ 1kΩ will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

NOTES:

FIGURE 4-2: MEMORY MAP FOR DEVICES WITH 128 KB OF PROGRAM MEMORY



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER (CONTINUED)

bit 2 **UFRCEN:** USB FRC Clock Enable bit(1)
- 1 = Enable FRC as the clock source for the USB clock source
- 0 = Use the Primary Oscillator or USB PLL as the USB clock source

bit 1 **SOSCEN:** Secondary Oscillator (SOSC) Enable bit
- 1 = Enable Secondary Oscillator
- 0 = Disable Secondary Oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
- 1 = Initiate an oscillator switch to selection specified by NOSC<2:0> bits
- 0 = Oscillator switch is complete

Note 1: This bit is available on PIC32MX4XX devices only.

Note:	Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 8-4: REFOTRIM: REFERENCE OSCILLATOR TRIM REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ROTRIM<8:1>							
23:16	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ROTRIM<0>	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:	y = Value set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-23 **ROTRIM<8:0>:** Reference Oscillator Trim bits

111111111 = 511/512 divisor added to RODIV value
111111110 = 510/512 divisor added to RODIV value
•
•
•
100000000 = 256/512 divisor added to RODIV value
•
•
•
000000010 = 2/512 divisor added to RODIV value
000000001 = 1/512 divisor added to RODIV value
000000000 = 0/512 divisor added to RODIV value

bit 22-0 **Unimplemented:** Read as '0'

Note: While the ON bit (REFOCON<15>) is '1', writes to this register do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 10-8: DCHxECON: DMA CHANNEL 'x' EVENT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHAIRQ<7:0>(1)							
15:8	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHSIRQ<7:0>(1)							
7:0	S-0	S-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
	CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—

Legend:	S = Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as '0'

bit 23-16 **CHAIRQ<7:0>:** Channel Transfer Abort IRQ bits(1)
- 11111111 = Interrupt 255 will abort any transfers in progress and set CHAIF flag
- •
- •
- •
- 00000001 = Interrupt 1 will abort any transfers in progress and set CHAIF flag
- 00000000 = Interrupt 0 will abort any transfers in progress and set CHAIF flag

bit 15-8 **CHSIRQ<7:0>:** Channel Transfer Start IRQ bits(1)
- 11111111 = Interrupt 255 will initiate a DMA transfer
- •
- •
- •
- 00000001 = Interrupt 1 will initiate a DMA transfer
- 00000000 = Interrupt 0 will initiate a DMA transfer

bit 7 **CFORCE:** DMA Forced Transfer bit
- 1 = A DMA transfer is forced to begin when this bit is written to a '1'
- 0 = This bit always reads '0'

bit 6 **CABORT:** DMA Abort Transfer bit
- 1 = A DMA transfer is aborted when this bit is written to a '1'
- 0 = This bit always reads '0'

bit 5 **PATEN:** Channel Pattern Match Abort Enable bit
- 1 = Abort transfer and clear CHEN on pattern match
- 0 = Pattern match is disabled

bit 4 **SIRQEN:** Channel Start IRQ Enable bit
- 1 = Start channel cell transfer if an interrupt matching CHSIRQ occurs
- 0 = Interrupt number CHSIRQ is ignored and does not start a transfer

bit 3 **AIRQEN:** Channel Abort IRQ Enable bit
- 1 = Channel transfer is aborted if an interrupt matching CHAIRQ occurs
- 0 = Interrupt number CHAIRQ is ignored and does not terminate a transfer

bit 2-0 **Unimplemented:** Read as '0'

Note 1: See **Table 7-1: "Interrupt IRQ, Vector and Bit Location"** for the list of available interrupt IRQ sources.

REGISTER 10-12: DCHxSSIZ: DMA CHANNEL 'x' SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

1111111111111111 = 65,535 byte source size
.
.
.
0000000000000010 = 2 byte source size
0000000000000001 = 1 byte source size
0000000000000000 = 65,536 byte source size

REGISTER 10-13: DCHxDSIZ: DMA CHANNEL 'x' DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

1111111111111111 = 65,535 byte destination size
.
.
.
0000000000000010 = 2 byte destination size
0000000000000001 = 1 byte destination size
0000000000000000 = 65,536 byte destination size

REGISTER 15-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	—	—	—	—	—	—
7:0	U-0	R-y	R-y	R-y	R-y	R-y	R/W-0	R/W-0
	—	SWDTPS<4:0>					WDTWINEN	WDTCLR

Legend:	y = Values set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Watchdog Timer Enable bit(1,2)
- 1 = Enables the WDT if it is not enabled by the device configuration
- 0 = Disable the WDT if it was enabled in software

bit 14-7 **Unimplemented:** Read as '0'

bit 6-2 **SWDTPS<4:0>:** Shadow Copy of Watchdog Timer Postscaler Value from Device Configuration bits
On reset, these bits are set to the values of the WDTPS <4:0> of Configuration bits.

bit 1 **WDTWINEN:** Watchdog Timer Window Enable bit
- 1 = Enable windowed Watchdog Timer
- 0 = Disable windowed Watchdog Timer

bit 0 **WDTCLR:** Watchdog Timer Reset bit
- 1 = Writing a '1' will clear the WDT
- 0 = Software cannot force this bit to a '0'

Note 1: A read of this bit results in a '1' if the Watchdog Timer is enabled by the device configuration or software.

2: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 18-2: SPIxCON2: SPI CONTROL REGISTER 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SPISGNEXT	—	—	FRMERREN	SPIROVEN	SPITUREN	IGNROV	IGNTUR
7:0	R/W-0	U-0	U-0	U-0	R/W-0	U-0	R/W-0	R/W-0
	AUDEN(1)	—	—	—	AUDMONO(1,2)	—	AUDMOD<1:0>(1,2)	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **SPISGNEXT:** Sign Extend Read Data from the RX FIFO bit
- 1 = Data from RX FIFO is sign extended
- 0 = Data from RX FIFO is not sign extened

bit 14-13 **Unimplemented:** Read as '0'

bit 12 **FRMERREN:** Enable Interrupt Events via FRMERR bit
- 1 = Frame Error overflow generates error events
- 0 = Frame Error does not generate error events

bit 11 **SPIROVEN:** Enable Interrupt Events via SPIROV bit
- 1 = Receive overflow generates error events
- 0 = Receive overflow does not generate error events

bit 10 **SPITUREN:** Enable Interrupt Events via SPITUR bit
- 1 = Transmit Underrun Generates Error Events
- 0 = Transmit Underrun Does Not Generates Error Events

bit 9 **IGNROV:** Ignore Receive Overflow bit (for Audio Data Transmissions)
- 1 = A ROV is not a critical error; during ROV data in the fifo is not overwritten by receive data
- 0 = A ROV is a critical error which stop SPI operation

bit 8 **IGNTUR:** Ignore Transmit Underrun bit (for Audio Data Transmissions)
- 1 = A TUR is not a critical error and zeros are transmitted until the SPIxTXB is not empty
- 0 = A TUR is a critical error which stop SPI operation

bit 7 **AUDEN:** Enable Audio CODEC Support bit(1)
- 1 = Audio protocol is enabled
- 0 = Audio protocol is disabled

bit 6-5 **Unimplemented:** Read as '0'

bit 3 **AUDMONO:** Transmit Audio Data Format bit(1,2)
- 1 = Audio data is mono (Each data word is transmitted on both left and right channels)
- 0 = Audio data is stereo

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **AUDMOD<1:0>:** Audio Protocol Mode bit(1,2)
- 11 = PCM/DSP mode
- 10 = Right Justified mode
- 01 = Left Justified mode
- 00 = I^2S mode

Note 1: This bit can only be written when the ON bit = 0.

2: This bit is only valid for AUDEN = 1.

REGISTER 22-1: RTCCON: RTC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	CAL<9:8>	
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CAL<7:0>							
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	SIDL	—	—	—	—	—
7:0	R/W-0	R-0	U-0	U-0	R/W-0	R-0	R-0	R/W-0
	RTSECSEL(3)	RTCCLKON	—	—	RTCWREN(4)	RTCSYNC	HALFSEC(5)	RTCOE

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-26 **Unimplemented:** Read as '0'

bit 25-16 **CAL<9:0>:** RTC Drift Calibration bits, which contain a signed 10-bit integer value
0111111111 = Maximum positive adjustment, adds 511 RTC clock pulses every one minute
•
•
•
0000000001 = Minimum positive adjustment, adds 1 RTC clock pulse every one minute
0000000000 = No adjustment
1111111111 = Minimum negative adjustment, subtracts 1 RTC clock pulse every one minute
•
•
•
1000000000 = Maximum negative adjustment, subtracts 512 clock pulses every one minute

bit 15 **ON:** RTCC On bit(1,2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Disables the PBCLK to the RTCC when CPU enters in Idle mode
0 = Continue normal operation in Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **RTSECSEL:** RTCC Seconds Clock Output Select bit(3)
1 = RTCC Seconds Clock is selected for the RTCC pin
0 = RTCC Alarm Pulse is selected for the RTCC pin

bit 6 **RTCCLKON:** RTCC Clock Enable Status bit
1 = RTCC Clock is actively running
0 = RTCC Clock is not running

bit 5-4 **Unimplemented:** Read as '0'

Note 1: The ON bit is only writable when RTCWREN = 1.
2: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
3: Requires RTCOE = 1 (RTCCON<0>) for the output to be active.
4: The RTCWREN bit can be set only when the write sequence is enabled.
5: This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

TABLE 28-1: DEVCFG: DEVICE CONFIGURATION WORD SUMMARY

Virtual Address (BFC0_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
2FF0	DEVCFG3	31:16	FVBUSONIO	FUSBIDIO	IOL1WAY	PMDL1WAY	—	—	—	—	—	—	—	—	—	FSRSSEL<2:0>			xxxx
		15:0	USERID<15:0>																xxxx
2FF4	DEVCFG2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	FPLLODIV<2:0>			xxxx
		15:0	UPLLEN(1)	—	—	—	—	UPLLIDIV<2:0>(1)			—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>			xxxx
2FF8	DEVCFG1	31:16	—	—	—	—	—	—	FWDTWINSZ<1:0>		FWDTEN	WINDIS	—	WDTPS<4:0>					xxxx
		15:0	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>		IESO	—	FSOSCEN	—	—	FNOSC<2:0>			xxxx
2FFC	DEVCFG0	31:16	—	—	—	CP	—	—	—	BWP	—	—	—	—	PWP<7:4>				xxxx
		15:0	PWP<3:0>				—	—	—	—	—	—	—	ICESEL<1:0>		JTAGEN	DEBUG<1:0>		xxxx

Legend: x = unknown value on Reset; — = reserved, write as '1'. Reset values are shown in hexadecimal.
Note 1: This bit is only available on devices with a USB module.

TABLE 28-2: DEVICE ID, REVISION, AND CONFIGURATION SUMMARY

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F200	CFGCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	IOLOCK	PMDLOCK	—	—	—	—	—	—	—	—	JTAGEN	TROEN	—	TDOEN	000B
F220	DEVID	31:16	VER<3:0>				DEVID<27:16>												xxxx(1)
		15:0	DEVID<15:0>																xxxx(1)
F230	SYSKEY	31:16	SYSKEY<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: Reset values are dependent on the device variant.

28.2 On-Chip Voltage Regulator

All PIC32MX330/350/370/430/450/470 devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX330/350/370/430/450/470 family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 28-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in **Section 31.1 "DC Characteristics"**.

Note:	It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

28.2.1 HIGH VOLTAGE DETECT (HVD)

The HVD module monitors the core voltage at the VCAP pin. If a voltage above the required level is detected on VCAP, the I/O pins are disabled and the device is held in Reset as long as the HVD condition persists. See parameter HV10 (VHVD) in Table 31-11 in **Section 31.1 "DC Characteristics"** for more information.

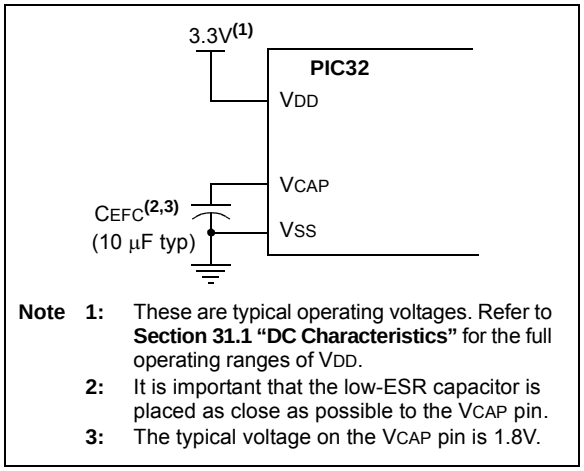
28.2.2 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

28.2.3 ON-CHIP REGULATOR AND BOR

PIC32MX330/350/370/430/450/470 devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 31.1 "DC Characteristics"**.

FIGURE 28-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 31.1 "DC Characteristics"** for the full operating ranges of VDD.

2: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

3: The typical voltage on the VCAP pin is 1.8V.

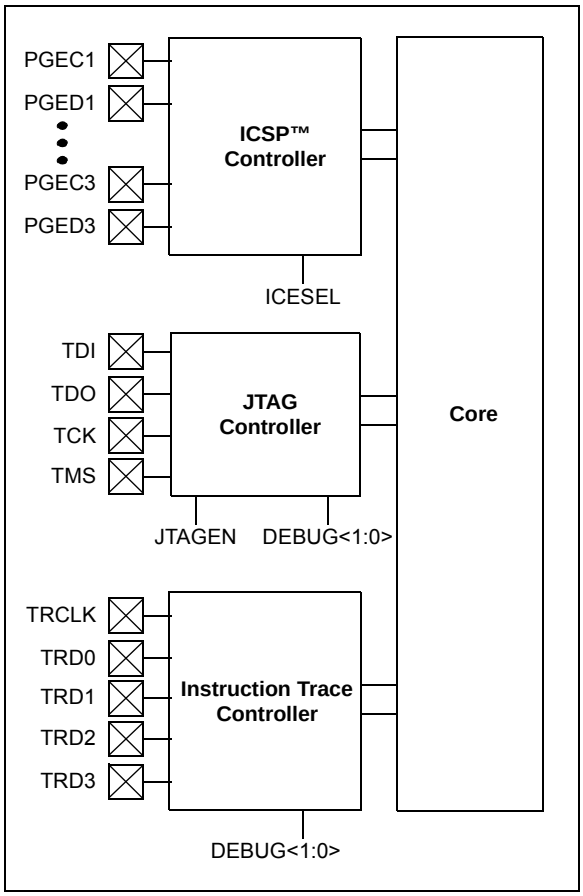
28.3 Programming and Diagnostics

PIC32MX330/350/370/430/450/470 devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

FIGURE 28-2: BLOCK DIAGRAM OF PROGRAMMING, DEBUGGING AND TRACE PORTS



30.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers (MCU) and dsPIC® digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® X IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB XC Compiler
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB X SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers/Programmers
  - MPLAB ICD 3
  - PICkit™ 3
- Device Programmers
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits and Starter Kits
- Third-party development tools

30.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows®, Linux and Mac OS® X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

30.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

30.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

30.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

30.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

30.10 MPLAB PM3 Device Programmer

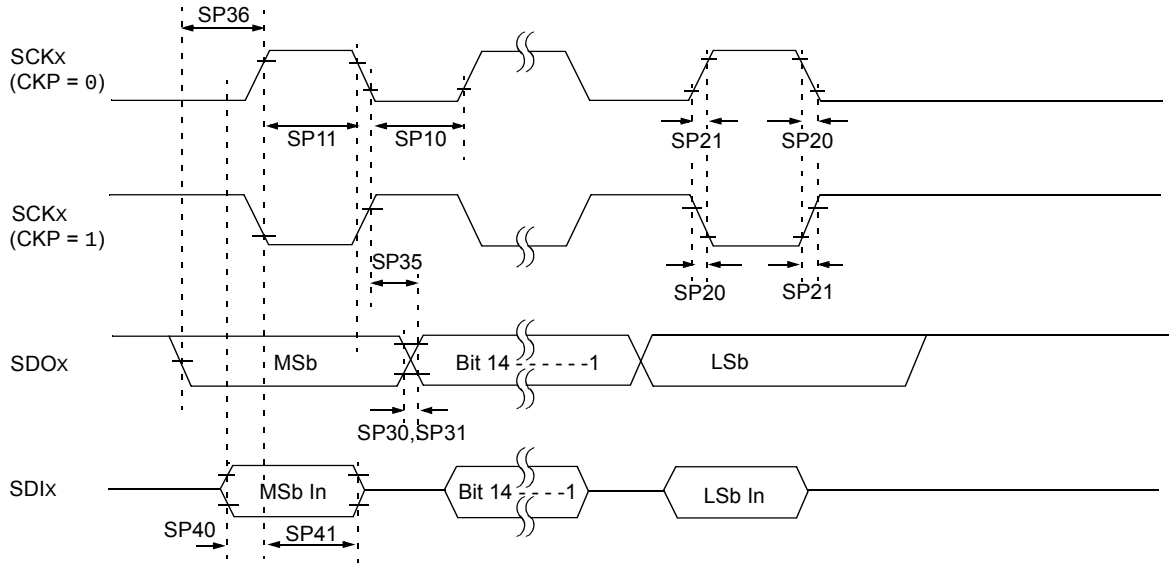
The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

TABLE 31-9: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 4x Sink Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	—	—	0.4	V	IOL ≤ 9 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - RC15, RD2, RD10, RF6, RG6	—	—	0.4	V	IOL ≤ 15 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Source Driver pins	2.4	—	—	V	IOH ≥ -10 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RC15, RD2, RD10, RF6, RG6	2.4	—	—	V	IOH ≥ -15 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 4x Source Driver Pins - All I/O output pins not defined as 8x Sink Driver pins	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - RC15, RD2, RD10, RF6, RG6	1.5(1)	—	—	V	IOH ≥ -22 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -18 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -10 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

FIGURE 31-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-30: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: VOH – 4x DRIVER PINS

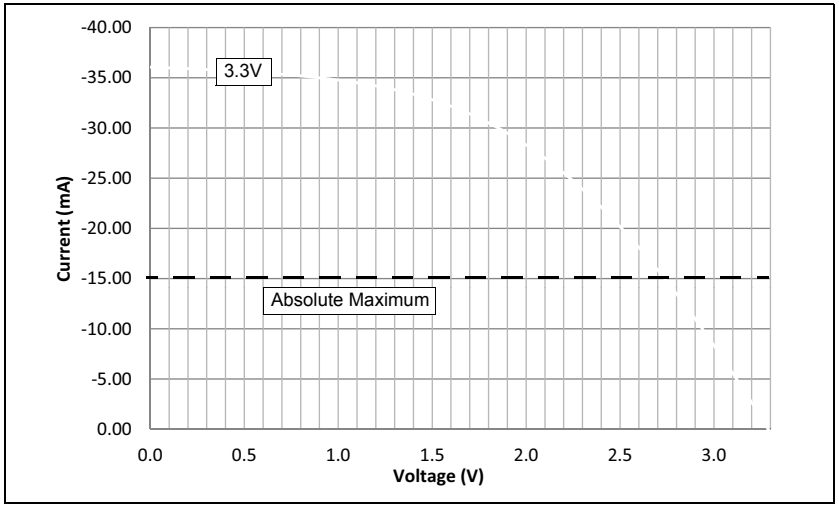


FIGURE 32-2: VOH – 8x DRIVER PINS

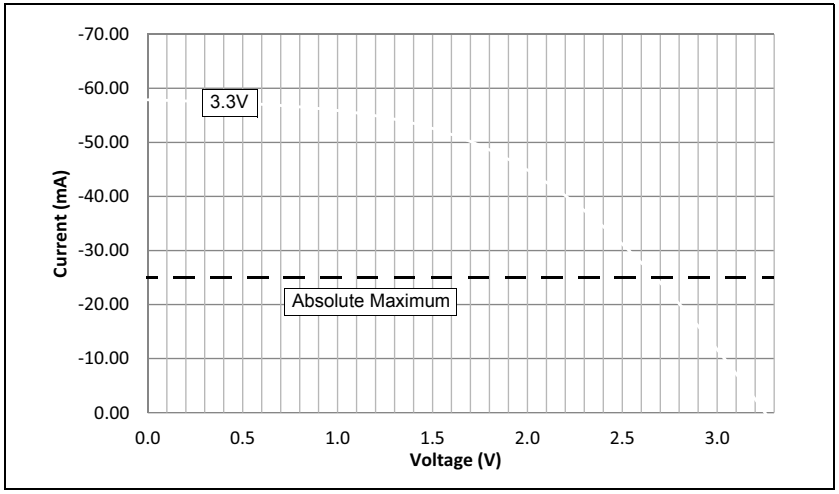


FIGURE 32-3: VOL – 4x DRIVER PINS

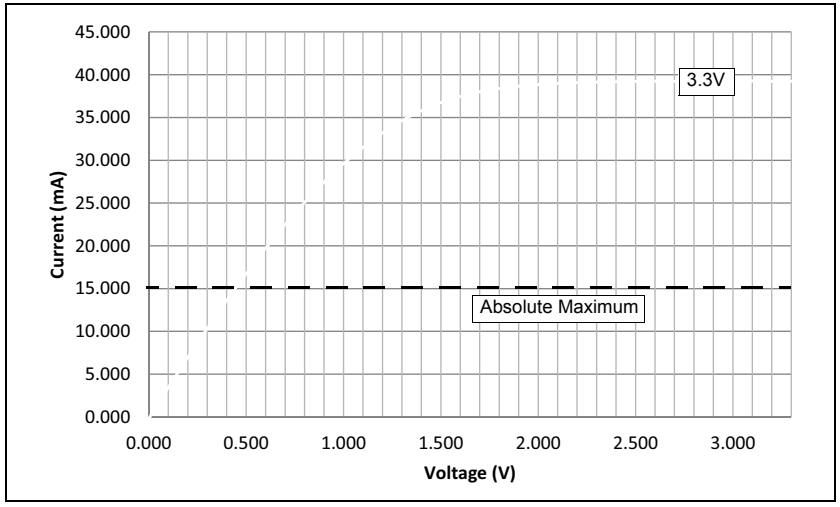
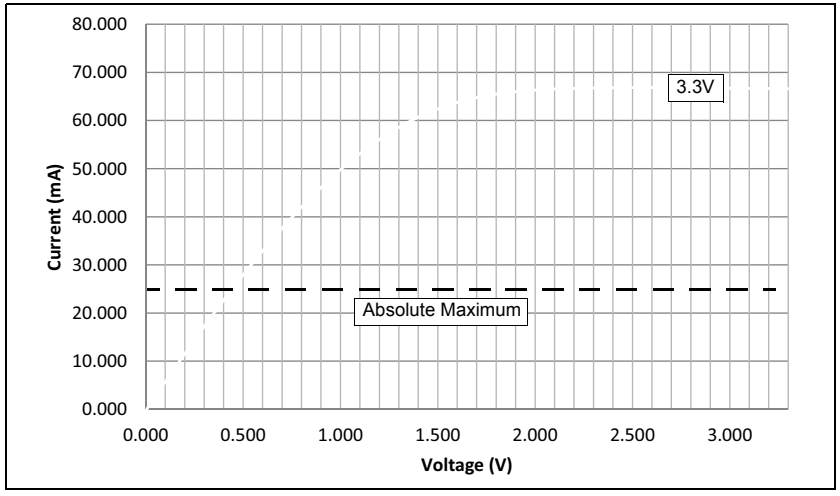
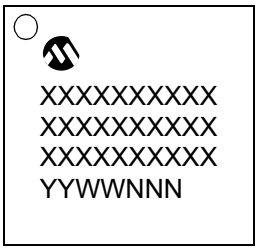


FIGURE 32-4: VOL – 8x DRIVER PINS

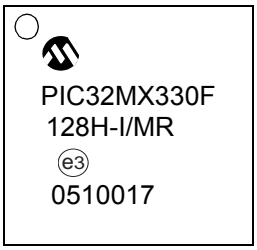


33.1 Package Marking Information (Continued)

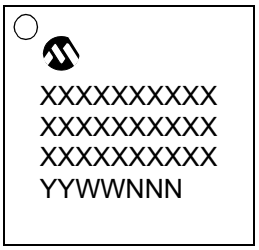
64-Lead QFN (9x9x0.9 mm) with 5.40x5.40 Exposed Pad



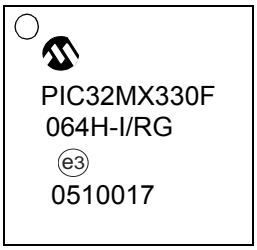
Example



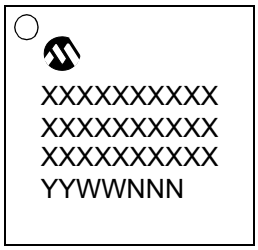
64-Lead QFN (9x9x0.9 mm) with 4.7x4.7 Exposed Pad



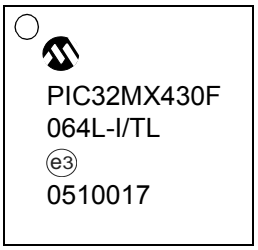
Example



124-Lead VTLA (9x9x0.9 mm)



Example

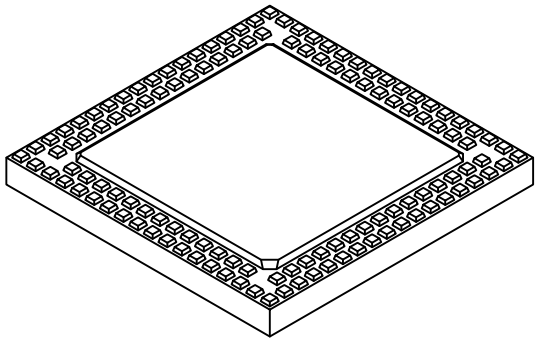


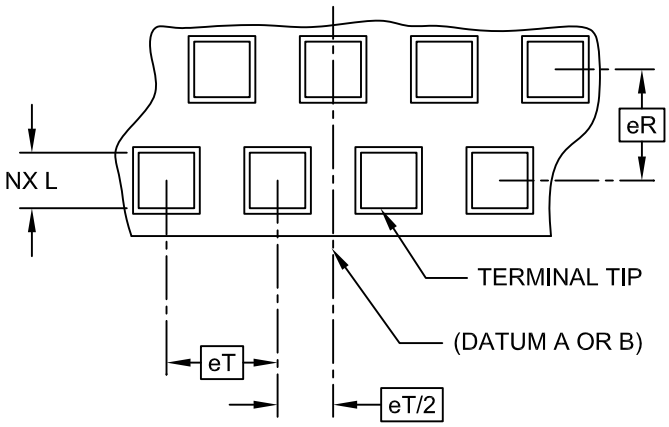
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
		Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

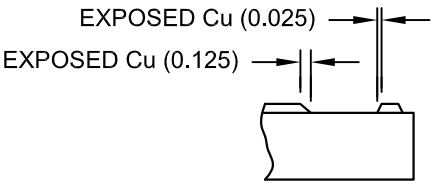
124-Terminal Very Thin Leadless Array Package (TL) – 9x9x0.9 mm Body [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





DETAIL A



SECTION B-B

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		124	
Pitch	eT		0.50 BSC	
Pitch (Inner to outer terminal ring)	eR		0.50 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	-	0.05
Overall Width	E		9.00 BSC	
Exposed Pad Width	E2	6.40	6.55	6.70
Overall Length	D		9.00 BSC	
Exposed Pad Length	D2	6.40	6.55	6.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-193A Sheet 2 of 2